

## Data Sheet

## **ADL5724**

### FEATURES

Frequency range: 12.7 GHz to 15.4 GHz

Typical gain of >23.7 dB

Low noise input

Noise figure

2.1 dB typical at 12.7 GHz

2.4 dB typical at 15.4 GHz

High linearity input

≥2.0 dBm typical input third-order intercept (IIP3)

-8 dBm input 1 dB compression point (P1dB) at 15.4 GHz

Matched 50 Ω single-ended input

Matched 100 Ω differential outputs

8-lead, 2.00 mm × 2.00 mm LFCSP microwave packaging

### APPLICATIONS

Point to point microwave radios

Instrumentation

Satellite communications (SATCOM)

Phased arrays

### GENERAL DESCRIPTION

The **ADL5724** is a narrow-band, high performance, low noise amplifier (LNA) targeting microwave radio link receiver designs. The monolithic silicon germanium (SiGe) design is optimized for microwave radio link bands ranging from 12.7 GHz to 15.4 GHz. The unique design offers a single-ended 50 Ω input impedance and provides a 100 Ω balanced differential output that is ideal for driving Analog Devices, Inc., differential downconverters and radio frequency (RF) sampling analog-to-digital converters (ADCs). This LNA provides noise figure performance that, in

### FUNCTIONAL BLOCK DIAGRAM

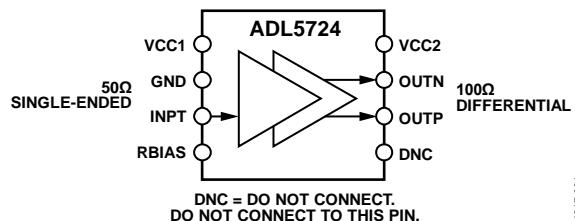


Figure 1.

14317-001

the past, required more expensive three-five (III-V) compounds process technology to achieve.

The **ADL5721** and **ADL5723** to **ADL5726** family of narrow-band LNAs are each packaged in a tiny, thermally enhanced, 2.00 mm × 2.00 mm LFCSP package. The **ADL5721** and **ADL5723** to **ADL5726** family operates over the temperature range of -40°C to +85°C.

## TABLE OF CONTENTS

Features .....	1	Typical Performance Characteristics .....	6
Applications.....	1	Theory of Operation .....	8
Functional Block Diagram .....	1	Applications Information .....	9
General Description .....	1	Layout .....	9
Revision History .....	2	Differential vs. Single-Ended Output .....	9
Specifications.....	3	Evaluation Board .....	10
AC Specifications.....	3	Initial Setup .....	10
DC Specifications .....	3	Results .....	10
Absolute Maximum Ratings.....	4	Basic Connections for Operation.....	11
Thermal Resistance .....	4	Outline Dimensions .....	12
ESD Caution.....	4	Ordering Guide .....	12
Pin Configuration and Function Descriptions.....	5		

## REVISION HISTORY

4/16—Revision 0: Initial Version

## SPECIFICATIONS

### AC SPECIFICATIONS

VCC1 = 1.8 V, VCC2 = 3.3 V, RBIAS = 442 Ω, TA = 25°C, ZSOURCE = 50 Ω, ZLOAD = 100 Ω differential, unless otherwise noted.

**Table 1.**

Parameter	Test Conditions/Comments	Min	Typ	Max	Unit
FREQUENCY RANGE		12.7		15.4	GHz
FREQUENCY = 12.7 GHz					
Gain (S21)		26.4			dB
Noise Figure		2.1			dB
Input Third-Order Intercept (IIP3)	Δf = 1 MHz, input power (P <sub>IN</sub> ) = -30 dBm per tone	2.0			dBm
Input 1 dB Compression Point (P1dB)		-11			dBm
Input Return Loss (S11)		10			dB
Output Return Loss (S22)		10			dB
FREQUENCY = 15.4 GHz					
Gain (S21)		23.7			dB
Noise Figure		2.4			dB
Input Third-Order Intercept (IIP3)	Δf = 1 MHz, P <sub>IN</sub> = -30 dBm per tone	4.0			dBm
Input 1 dB Compression Point (P1dB)		-8			dBm
Input Return Loss (S11)		7			dB
Output Return Loss (S22)		10			dB

### DC SPECIFICATIONS

**Table 2.**

Parameter	Test Conditions/Comments	Min	Typ	Max	Unit
POWER INTERFACE					
Voltage					
VCC1		1.65	1.8	1.95	V
VCC2		3.1	3.3	3.5	V
Quiescent Current vs. Temperature					
VCC1	T <sub>A</sub> = 25°C -40°C ≤ T <sub>A</sub> ≤ +85°C	19.4			mA
VCC2	T <sub>A</sub> = 25°C -40°C ≤ T <sub>A</sub> ≤ +85°C	90.0			mA
		90.3			mA

## ABSOLUTE MAXIMUM RATINGS

Table 3.

Parameter	Rating
Supply Voltages	
VCC1	2.25 V
VCC2	4.1 V
Maximum Junction Temperature	150°C/W
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-55°C to +125°C
Lead Temperature Range (Soldering, 60 sec)	-65°C to +150°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

## THERMAL RESISTANCE

$\theta_{JA}$  is thermal resistance, junction to ambient (°C/W),  $\theta_{JB}$  is thermal resistance, junction to board (°C/W), and  $\theta_{JC}$  is thermal resistance, junction to case (°C/W).

Table 4. Thermal Resistance

Package Type	$\theta_{JA}^1$	$\theta_{JB}^1$	$\theta_{JC}^1$	Unit
8-Lead LFCSP	39.90	23.88	3.71	°C/W

<sup>1</sup> See JEDEC standard JESD51-2 for additional information on optimizing the thermal impedance for a printed circuit board (PCB) with 3 × 4 vias.

## ESD CAUTION



### ESD (electrostatic discharge) sensitive device.

Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

## PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

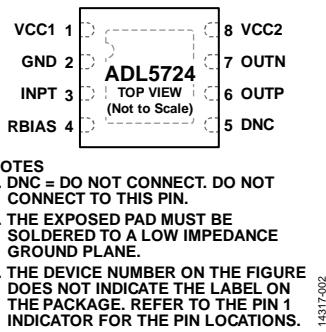
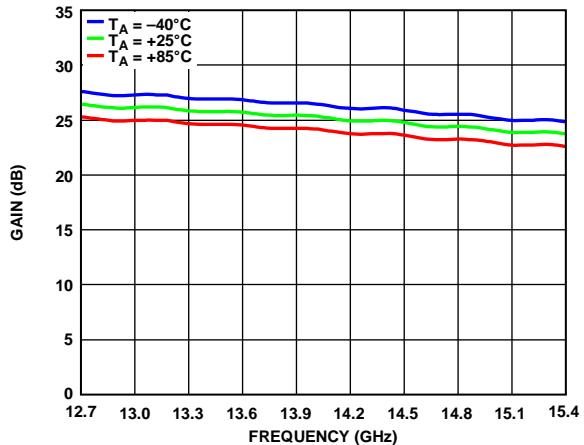


Figure 2. Pin Configuration

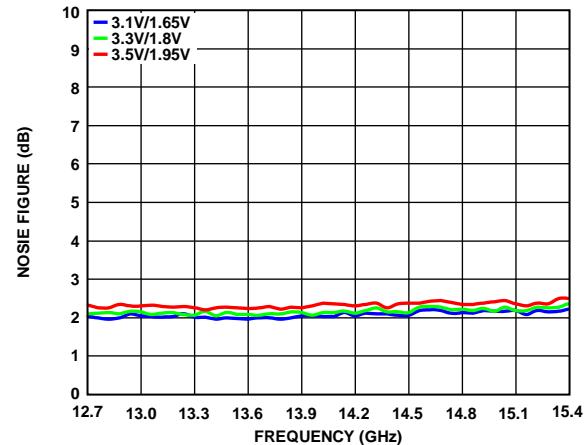
**Table 5. Pin Function Descriptions**

Pin No.	Mnemonic	Description
1	VCC1	1.8 V Power Supply. It is recommended to place the decoupling capacitors as close to this pin as possible.
2	GND	Ground.
3	INPT	RF Input. This is a $50\ \Omega$ single-ended input.
4	RBIAS	Resistor Bias. For typical operation, connect a $442\ \Omega$ resistor from RBIAS to GND. It is recommended to place the RBIAS resistor as close to the pin as possible.
5	DNC	Do Not Connect. Do not connect to this pin.
6, 7	OUTP, OUTN	RF Outputs. These pins are $100\ \Omega$ differential outputs.
8	VCC2 EPAD (EP)	3.3 V Power Supply. It is recommended to place the decoupling capacitors as close to this pin as possible. Exposed Pad. The exposed pad must be soldered to a low impedance ground plane.

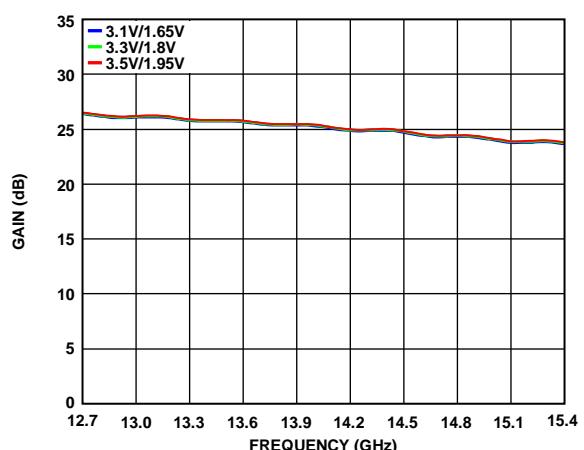
## TYPICAL PERFORMANCE CHARACTERISTICS



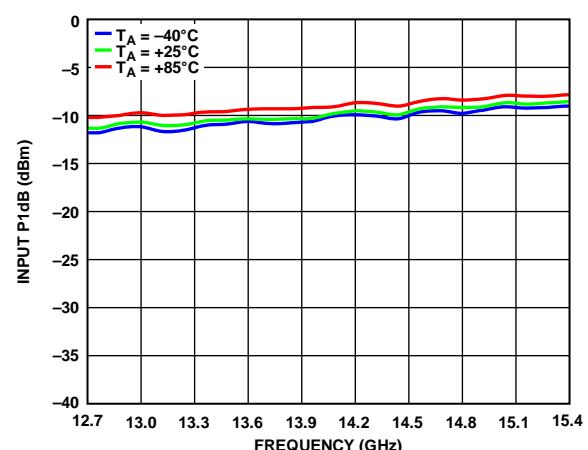
14317-003



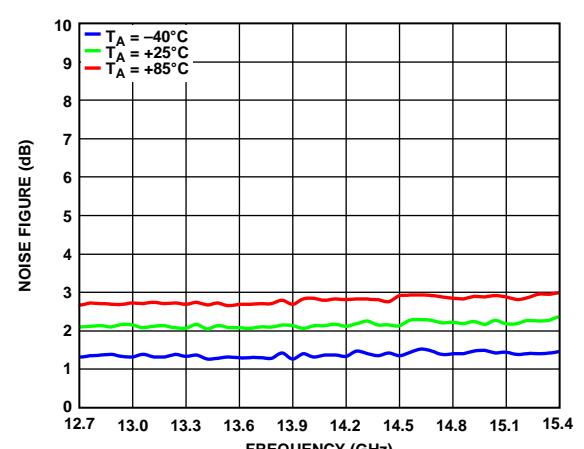
14317-006



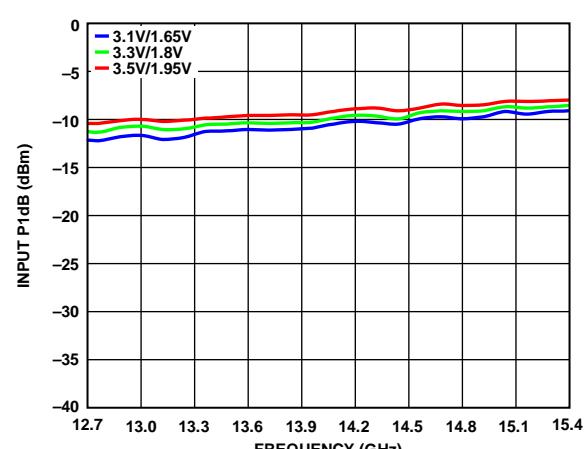
14317-004



14317-007



14317-005



14317-008

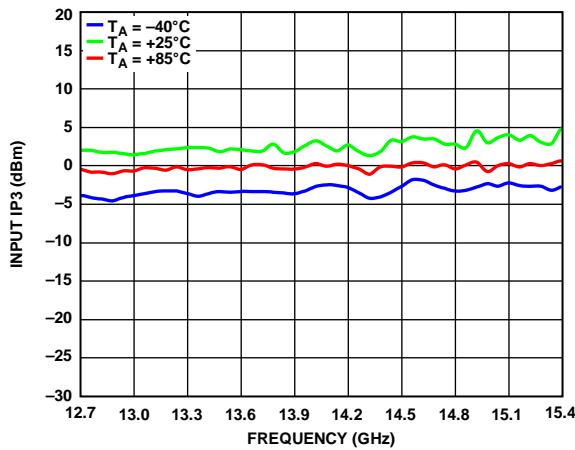


Figure 9. Input IP3 vs. Frequency for Various Temperatures

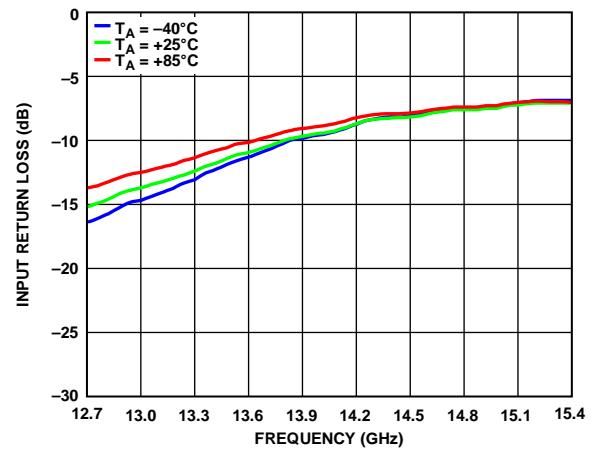


Figure 11. Input Return Loss vs. Frequency for Various Temperatures

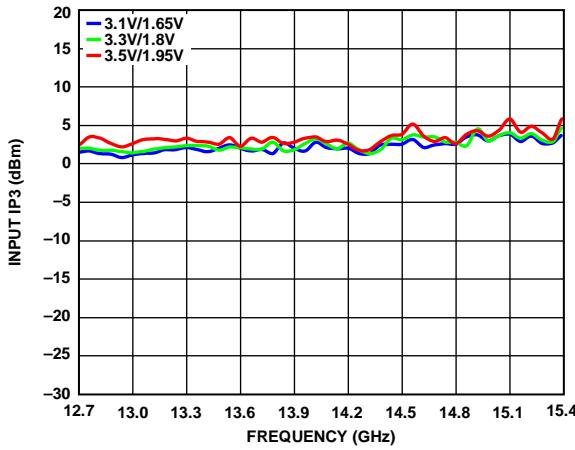


Figure 10. Input IP3 vs. Frequency for Various Supply Voltages

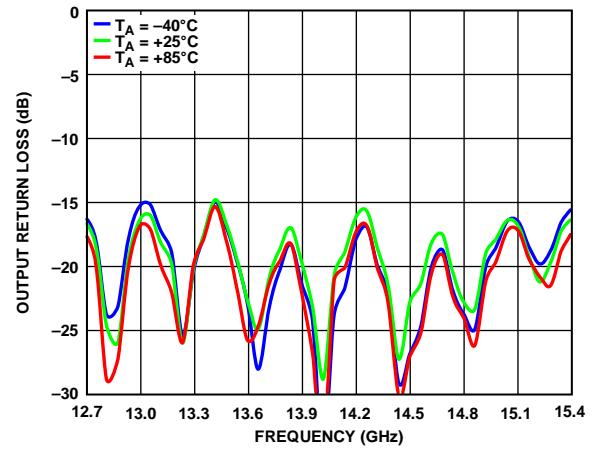


Figure 12. Output Return Loss vs. Frequency for Various Temperatures

## THEORY OF OPERATION

The [ADL5724](#) is a narrow-band, high performance, low noise amplifier targeting microwave radio link receiver designs. The monolithic SiGe design is optimized for microwave radio link bands ranging from 12.7 GHz to 15.4 GHz.

The unique design of the [ADL5724](#) offers a single-ended 50 Ω input impedance via the INPT pin, and provides a 100 Ω balanced differential output via the OUTP and OUTN pins.

This LNA is ideal for driving Analog Devices differential downconverters and RF sampling ADCs.

The [ADL5724](#) provides cost-effective noise figure performance without requiring more expensive III-V compounds process technology.

The [ADL5724](#) is available in a 2.00 mm × 2.00 mm LFCSP package, and operates over the temperature range of –40°C to +85°C.

## APPLICATIONS INFORMATION

### LAYOUT

Solder the exposed pad on the underside of the ADL5724 to a low thermal and electrical impedance ground plane. This pad is typically soldered to an exposed opening in the solder mask on the evaluation board. Connect the ground vias to all other ground layers on the evaluation board to maximize heat dissipation from the device package.

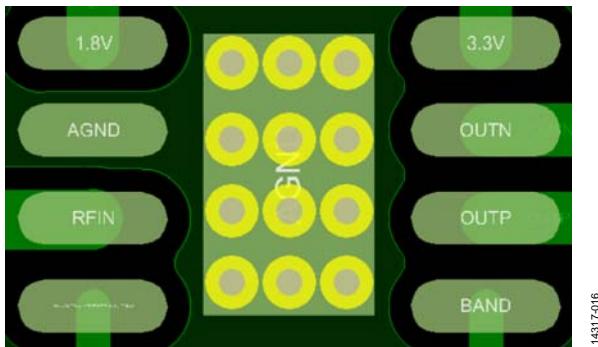


Figure 13. Evaluation Board Layout for the ADL5724 Package

### DIFFERENTIAL vs. SINGLE-ENDED OUTPUT

This section provides the test results that compare the ADL5724 using a differential vs. a single-ended output. When using the device as a single-ended output, use the RFOP output on the evaluation board and terminate RFON to  $50\ \Omega$ . Note that the converse can be done as well; however, doing so produces slightly different results from the plots shown in this section because there is some amplitude imbalance between the two differential ports, RFOP and RFON. The output trace and connector loss were not deembedded for these measurements.

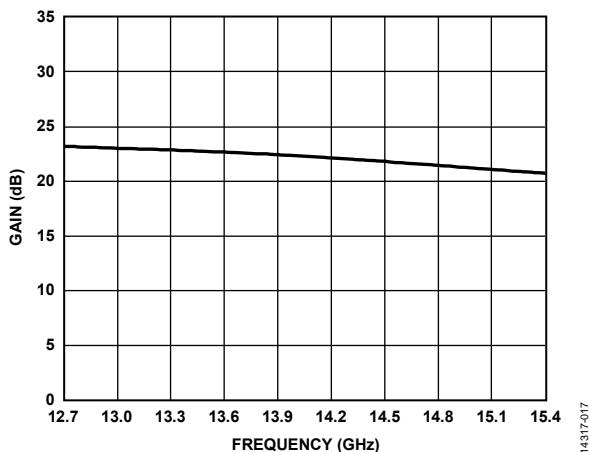


Figure 14. Gain vs. Frequency

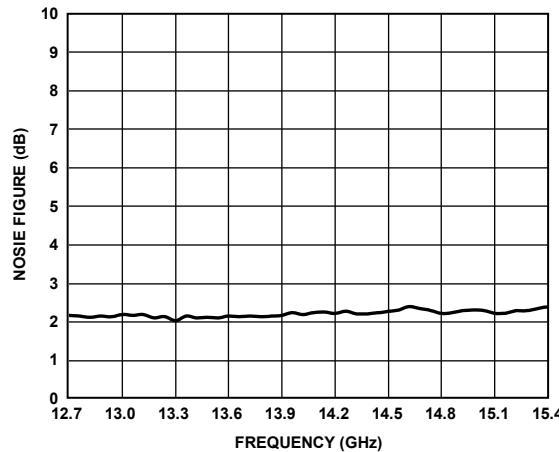


Figure 15. Noise Figure vs. Frequency

14317-018

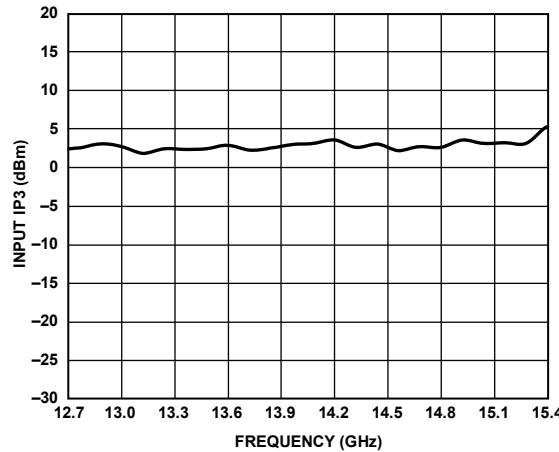


Figure 16. Input IP3 vs. Frequency

14317-021

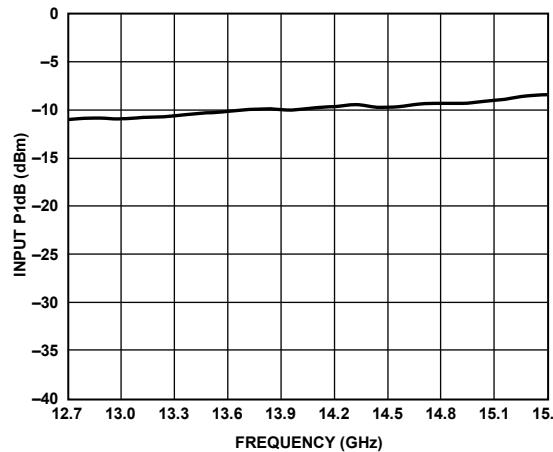


Figure 17. Input P1dB vs. Frequency

14317-020

## EVALUATION BOARD

The ADL5724-EVALZ comes with an ADL5724 chip. It supports a single 5 V supply for ease of use. Note that, for 5 V operation, the 3.3 V and 1.8 V test loops are for evaluation purposes only. When using a 3.3 V or 1.8 V supply, remove the R1 and R2 resistors from the evaluation board. Figure 19 shows the ADL5724-EVALZ lab bench setup.

### INITIAL SETUP

To set up the ADL5724-EVALZ, take the following steps:

1. Power up the ADL5724-EVALZ with a 5 V dc supply. The supply current of the evaluation board is approximately 114 mA, which is a combination of the VCC1 (1.8 V) and the VCC2 (3.3 V) currents.
2. Connect the signal generator to the input of the ADL5724-EVALZ.
3. Connect RFOP and RFON to a 180° hybrid that works within the 12.7 GHz to 15.4 GHz frequency range.
4. Connect the difference output of the hybrid to the spectrum analyzer. The sum port of the hybrid must be terminated to 50 Ω.

See Figure 19 for the ADL5724-EVALZ lab bench setup.

## RESULTS

Figure 18 shows the expected results when testing the ADL5724-EVALZ using the Rev. A version of the evaluation board and its software. Note that future iterations of the software may produce different results. See the ADL5724 product page for the most recent software version.

Figure 18 shows the results of differential output for an input of 12.7 GHz at -15 dBm. The hybrid and board loss were not deembedded.

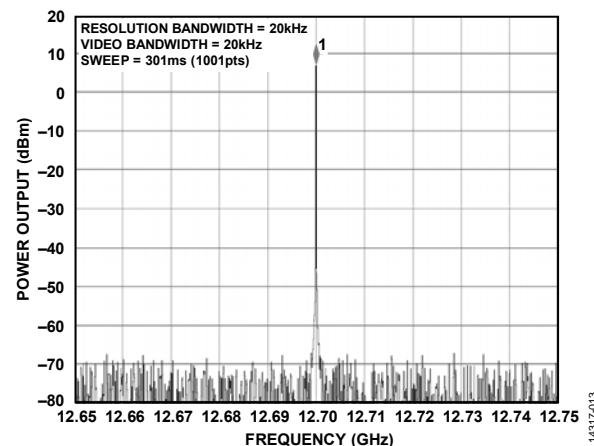
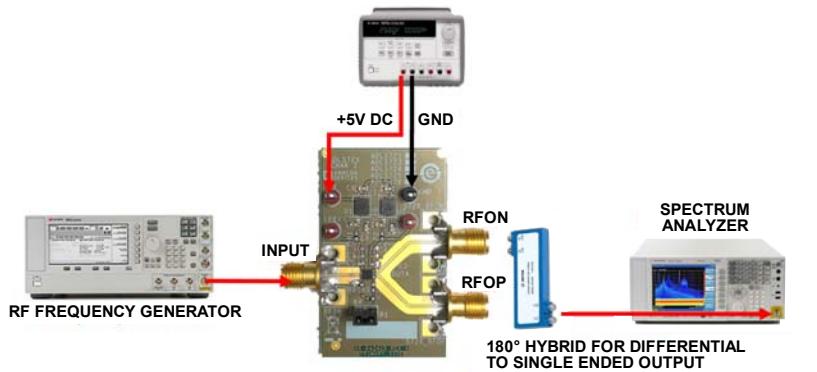


Figure 18. Test Results at 12.7 GHz

14317-013



14317-014

Figure 19. ADL5724-EVALZ Lab Bench Setup

**BASIC CONNECTIONS FOR OPERATION**

Figure 20 shows the basic connections for operating the ADL5724 as it is implemented on the evaluation board of the device.

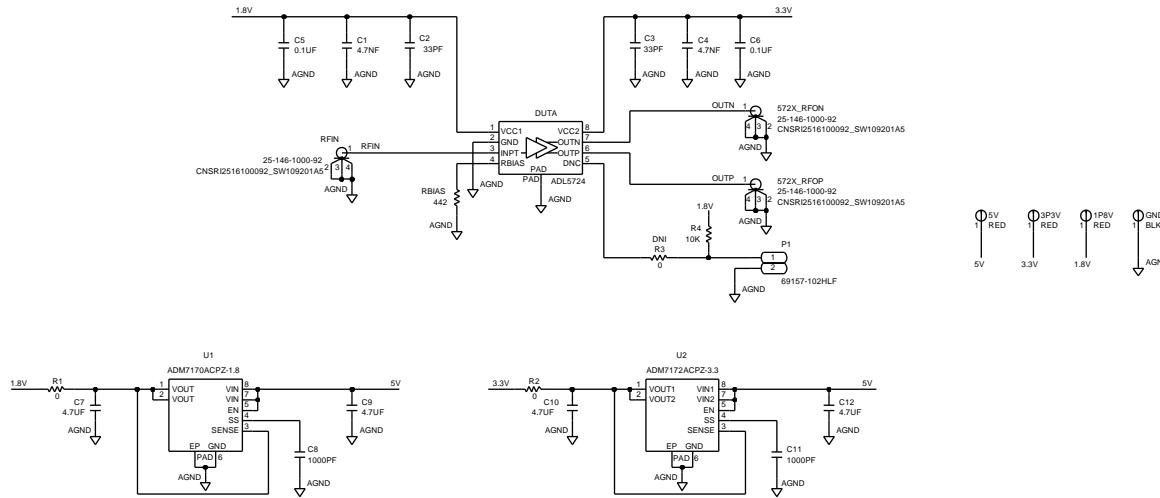


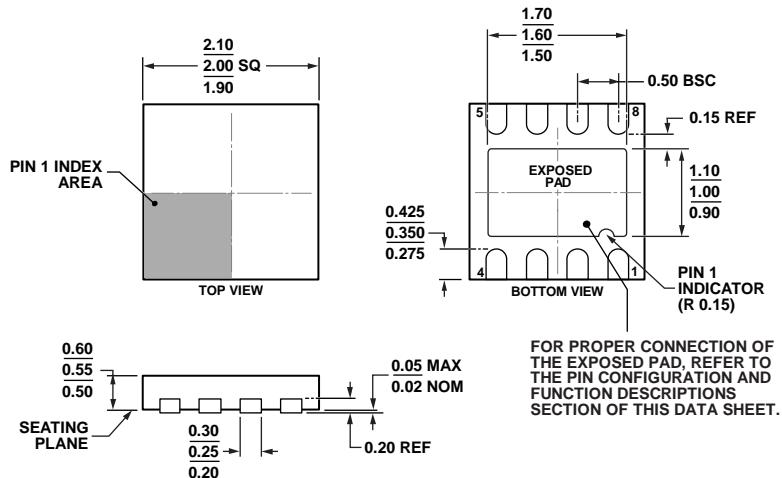
Figure 20. Evaluation Board Schematic

14317-015

Table 6. Evaluation Board Configuration Options

Component	Function	Default Condition
3P3V, 1P8V, GND, 5V	Power supplies and ground.	Not applicable
RFIN, 572X_RFOP, 572x_RFON	Input, output, and data.	Not applicable
RBIAS	442 Ω for RBIAS.	R1 = 442 Ω (0402)
R1,R2	1.8 V and 3.3 V regulator connections.	R2 = 0 Ω (0402)
R3	Do not install (DNI).	R3 = DNI (0402)
R4	Pull-up or pull-down resistor.	R4 = 10 kΩ (0402)
C1 to C12	The capacitors provide the required decoupling of the supply related pins.	C1, C4 = 4.7 nF (0402), C2, C3 = 33 pF (0402), C5, C6 = 0.1 µF (0402), C7, C9, C10, C12 = 4.7 µF (0603), C8,C11 = 1000 pF (0603)
P1	Jumper to change bands, 2-pin jumper.	Not applicable
U1	ADM7170ACPZ-1.8 1.8 V regulator.	Not applicable
U2	ADM7172ACPZ-3.3 3.3 V regulator.	Not applicable
DTUA	ADL5724 device under test (DUT).	Not applicable

## OUTLINE DIMENSIONS



01-14-2013-C

Figure 21. 8-Lead Lead Frame Chip Scale Package [LFCSP]  
2.00 mm × 2.00 mm Body, and 0.55 mm Package Height  
(CP-8-10)

Dimensions shown in millimeters

## ORDERING GUIDE

Model <sup>1</sup>	Temperature Range	Package Description	Package Option
ADL5724ACPZN-R7	−40°C to +85°C	8-Lead Lead Frame Chip Scale Package [LFCSP]	CP-8-10
ADL5724-EVALZ		Evaluation Board	

<sup>1</sup>Z = RoHS-Compliant Part.



**Стандарт  
Электрон  
Связь**

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию .

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России , а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научно-исследовательскими институтами России.

С нами вы становитесь еще успешнее!

**Наши контакты:**

**Телефон:** +7 812 627 14 35

**Электронная почта:** [sales@st-electron.ru](mailto:sales@st-electron.ru)

**Адрес:** 198099, Санкт-Петербург,  
Промышленная ул, дом № 19, литер Н,  
помещение 100-Н Офис 331